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No.	Database	Search term	Info added since	Results	
1	INZZ	frame\$1 AND mirror\$1 AND gimbal\$1	unrestricted	7	<a href="#">show titles</a>
2	INZZ	frame\$1 AND mirror\$1 AND gimbal\$1 AND (axis OR axes)	unrestricted	6	<a href="#">show titles</a>
3	INZZ	frame\$1 AND mirror\$1 AND gimbal\$1 AND second WITH (axis OR axes) AND truss	unrestricted	0	-
4	INZZ	wafer\$1 AND oxide AND layer\$1 AND first AND second	unrestricted	49	<a href="#">show titles</a>
5	INZZ	silicon ADJ insulator ADJ wafer\$1 AND oxide AND first AND second	unrestricted	0	-

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- ☐ Classification codes A: Physics, 7
- ☐ Classification codes A: Physics, 8
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- ☐ Classification codes D: Information Technology, 0-9
- ☐ Treatment codes
- ☐ INSPEC sub-file
- ☐ Publication types
- ☐ Language of publication

**Updated Search Query Case No. 10/026,318**

826	frame\$1 and mirror\$1 and gimbal\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
754	(frame\$1 and mirror\$1 and gimbal\$1) and (axis or axes)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
411	((frame\$1 and mirror\$1 and gimbal\$1) and (second with (axis or axes)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
0	((frame\$1 and mirror\$1 and gimbal\$1) and (second with (axis or axes))) and truss	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
3	((frame\$1 and mirror\$1 and gimbal\$1) and (second with (axis or axes))) and truss\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
15	frame\$1 and mirror\$1 and (gimbal\$1 adj portion\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
44121	wafer\$1 and oxide and layer\$1 and first and second	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
268	silicon adj insulator adj wafer\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
201	(silicon adj insulator adj wafer\$1) and oxide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
159	((silicon adj insulator adj wafer\$1) and oxide) and first and second	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
118	((silicon adj insulator adj wafer\$1) and oxide) and ((first and second) with layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
99	((silicon adj insulator adj wafer\$1) and oxide) and ((first and second) with layer)) and (pattern\$ or etch)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

8	(((((silicon adj insulator adj wafer\$1) and oxide) and ((first and second) with layer)) and (pattern\$ or etch)) and frame\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
623	(385/18).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
978	(141/1).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
835	(501/88).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
1000	(250/234).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
466	(216/22).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
3902	((385/18).CCLS.) or ((141/1).CCLS.) or ((501/88).CCLS.) or ((250/234).CCLS.) or ((216/22).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
216	(((((385/18).CCLS.) or ((141/1).CCLS.) or ((501/88).CCLS.) or ((250/234).CCLS.) or ((216/22).CCLS.)) and frame\$1 and mirror\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
0	(((((385/18).CCLS.) or ((141/1).CCLS.) or ((501/88).CCLS.) or ((250/234).CCLS.) or ((216/22).CCLS.)) and frame\$1 and mirror\$1) and gimbal\$1) and truss\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
28	(((((385/18).CCLS.) or ((141/1).CCLS.) or ((501/88).CCLS.) or ((250/234).CCLS.) or ((216/22).CCLS.)) and frame\$1 and mirror\$1) and gimbal\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
1	mirror adj rocking adj member adj optical adj deflector	USPAT; US-PGPUB
785	frame\$1 and gimbal\$1 and mirror\$1	USPAT; US-PGPUB
680	(frame\$1 and gimbal\$1 and mirror\$1 ) and first and second and axis	USPAT; US-PGPUB
9	((frame\$1 and gimbal\$1 and mirror\$1 ) and first and second and axis ) and (outer adj frame adj portion)	USPAT; US-PGPUB
0	(((((frame\$1 and gimbal\$1 and mirror\$1 ) and first and second and axis ) and (outer adj frame adj portion)) and (resonant adj frequenc\$3)	USPAT; US-PGPUB
0	(((((frame\$1 and gimbal\$1 and mirror\$1 ) and first and second and axis ) and (outer adj frame adj portion)) and (resonant adj frequency)	USPAT; US-PGPUB

9	((frame\$1 and gimbal\$1 and mirror\$1 ) and first and second and axis ) and (outer adj frame adj portion)) and (mirror adj portion)	USPAT; US-PGPUB
2	((frame\$1 and gimbal\$1 and mirror\$1 ) and first and second and axis ) and (outer adj frame adj portion)) and ((mirror adj portion) with mm)	USPAT; US-PGPUB
7	((frame\$1 and gimbal\$1 and mirror\$1 ) and first and second and axis ) and (outer adj frame adj portion)) and mm	USPAT; US-PGPUB
1	("6295154").PN.	USPAT
172	(frame\$1 and gimbal\$1 and mirror\$1 ) and (frame\$1 same gimbal\$1 with frame\$1)	USPAT
1	((("6295154").PN.) and (frame\$1 same gimbal\$1 with frame\$1)	USPAT
1	((("6295154").PN.) and (frame\$1 same gimbal\$1 with mirror\$1)	USPAT
1	((("6295154").PN.) and magnet\$1	USPAT
1	((("6295154").PN.) and (magnet\$1 with opposite)	USPAT
1	((("6295154").PN.) and (magnet\$1 with opposite with symmetric\$)	USPAT
1	((("6295154").PN.) and (single with piece with material)	USPAT
1	((("6295154").PN.) and (switch\$ with station\$1)	USPAT
1	((("6295154").PN.) and (mirror adj portion)	USPAT
0	((("6295154").PN.) and (mirror with frame with gimbal with thick\$)	USPAT
1	((frame\$1 and gimbal\$1 and mirror\$1 ) and first and second and axis ) and (outer adj frame adj portion)) and ((mirror adj portion) with thick\$4)	USPAT; US-PGPUB
3111	(359/198,213,214,223,224,230,290,291,298).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
3346	(310/36,90).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
627	(73/504.02,504.12).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
787	(335/222,223,229).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
7781	((359/198,213,214,223,224,230,290,291,298).CCLS.) or ((310/36,90).CCLS.) or ((73/504.02,504.12).CCLS.) or ((335/222,223,229).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
920	frame\$1 and mirror\$1 and gimbal\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

840	(frame\$1 and mirror\$1 and gimbal\$1) and (axis or axes)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
470	(frame\$1 and mirror\$1 and gimbal\$1) and (second with (axis or axes))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
1	((frame\$1 and mirror\$1 and gimbal\$1) and (second with (axis or axes))) and truss	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
19	frame\$1 and mirror\$1 and (gimbal\$1 adj portion\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
52371	wafer\$1 and oxide and layer\$1 and first and second	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
347	silicon adj insulator adj wafer\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
260	(silicon adj insulator adj wafer\$1) and oxide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
209	((silicon adj insulator adj wafer\$1) and oxide) and first and second	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
150	((silicon adj insulator adj wafer\$1) and oxide) and ((first and second) with layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
125	((silicon adj insulator adj wafer\$1) and oxide) and ((first and second) with layer)) and (pattern\$ or etch)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
13	((silicon adj insulator adj wafer\$1) and oxide) and ((first and second) with layer)) and (pattern\$ or etch)) and frame\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
4449	((385/18).CCLS.) or ((141/1).CCLS.) or ((501/88).CCLS.) or ((250/234).CCLS.) or ((216/22).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
277	((385/18).CCLS.) or ((141/1).CCLS.) or ((501/88).CCLS.) or ((250/234).CCLS.) or ((216/22).CCLS.)) and frame\$1 and mirror\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

0	(((385/18).CCLS.) or ((141/1).CCLS.) or ((501/88).CCLS.) or ((250/234).CCLS.) or ((216/22).CCLS.)) and frame\$1 and mirror\$1) and gimbal\$1) and truss\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
41	(((385/18).CCLS.) or ((141/1).CCLS.) or ((501/88).CCLS.) or ((250/234).CCLS.) or ((216/22).CCLS.)) and frame\$1 and mirror\$1) and gimbal\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
12	((frame\$1 and gimbal\$1 and mirror\$1 ) and first and second and axis ) and (outer adj frame adj portion)	USPAT; US-PGPUB
13	((frame\$1 and gimbal\$1 and mirror\$1 ) and first and second and axis ) and (outer adj frame adj portion)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
42	(((359/198,213,214,223,224,230,290,291,298).CCLS.) or ((310/36,90).CCLS.) or ((73/504.02,504.12).CCLS.) or ((335/222,223,229).CCLS.)) and ((frame\$1 and mirror\$1 and gimbal\$1) and (second with (axis or axes)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

**Search Results Case No. 10/026,318**

US 20030117685 A1	US-PGPUB	Micromirror truss structure and fabrication method	359/291
US 6295154 B1	USPAT	Optical switching apparatus	359/223
US 20020141036 A1	US-PGPUB	Device for use with a micro-electro-mechanical system (MEMS) optical device and a method of manufacture therefor	359/291
US 6454421 B2	USPAT	Dual axis micro machined mirror device	359/872
US 6480320 B2	USPAT	Microelectromechanical mirror and mirror array	359/291
US 20020012180 A1	US-PGPUB	Dual axis micro-machined mirror device	359/872
US 20020054422 A1	US-PGPUB	Packaged MEMs device and method for making the same	359/291
US 20020071166 A1	US-PGPUB	Magnetically packaged optical MEMs device and method for making the same	359/224
US 20020075553 A1	US-PGPUB	Packaged micromirror assembly with in-package mirror position passive component feedback	359/290
US 20020181110 A1	US-PGPUB	Device having a barrier layer located therein and a method of manufacture therefor	359/599
US 20020095618 A1	US-PGPUB	Optical wireless network printed circuit board micromirror assembly having in-package mirror position feedback	714/10
US 6392220 B1	USPAT	Micromachined members coupled for relative rotation by hinges	250/216
US 5606447 A	USPAT	Planar type mirror galvanometer and method of manufacture	359/199
US 20020074310 A1	US-PGPUB	Method of fabricating a cooperating array of rotatable microstructure devices	216/22
US 20020118518 A1	US-PGPUB	Conductive member grid array interface for mirror array drive apparatus	361/748
US 20020034026 A1	US-PGPUB	Molded packages for optical wireless network micromirror assemblies	359/877
US 20020070335 A1	US-PGPUB	Packaged micromirror assembly with in-package mirror position feedback	250/234
US 6430332 B1	USPAT	Optical switching apparatus	385/18
US 20020018615 A1	US-PGPUB	Optical switching apparatus	385/18
US 20020034024 A1	US-PGPUB	Stacked micromirror structures	359/846
US 20020074310 A	DERWENT	Fabrication of microstructure array, e.g. micromirror array for wireless network system, comprises fabricating carrier wafer, mounting structure wafer, etching openings through and attaching permanent magnets to structure wafer	